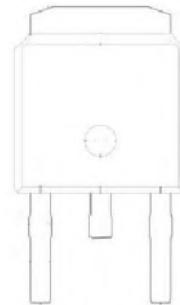
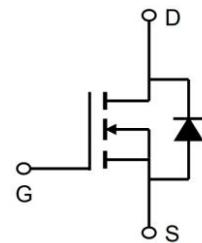


**30V N-Channel Enhancement Mode MOSFET**
**Description**

The 80N03D uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.


**General Features**

$V_{DS} = 30V$   $I_D = 80 A$

$R_{DS(ON)} < 6m\Omega$  @  $V_{GS}=10V$

**Application**

Battery protection

Load switch

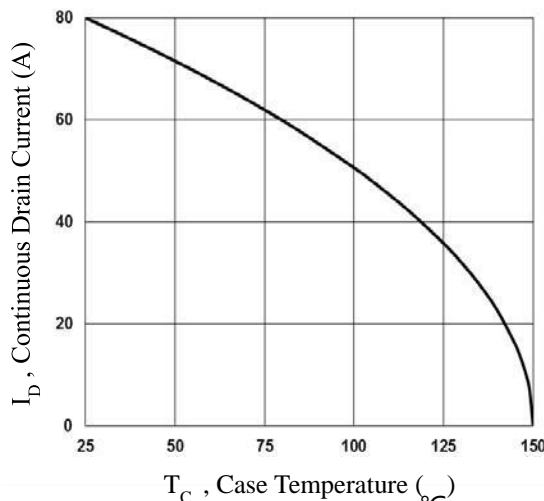
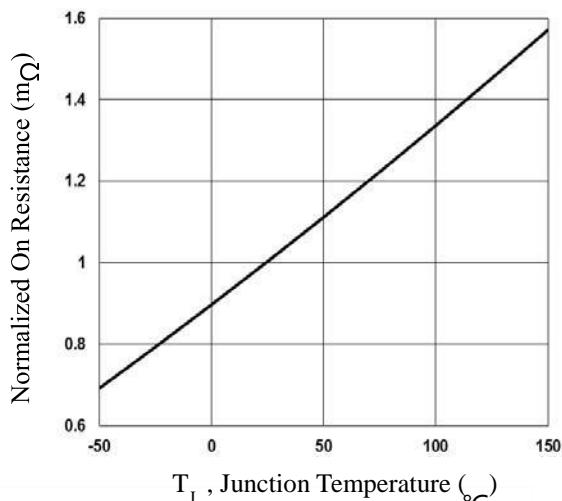
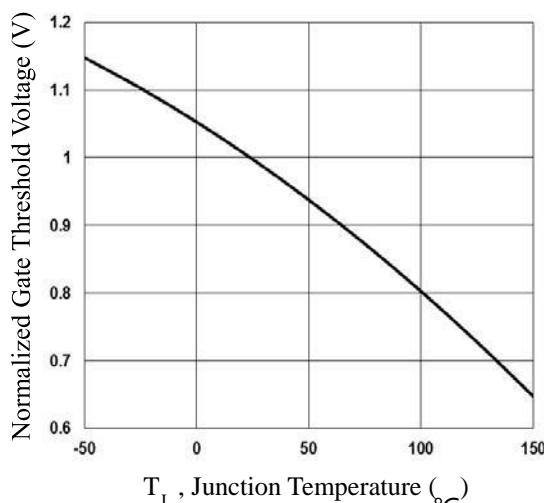
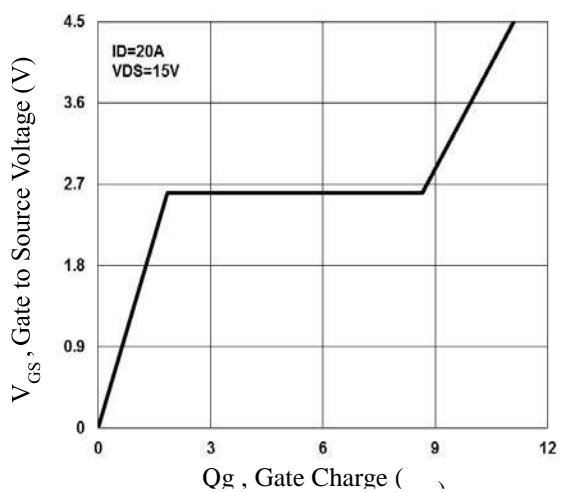
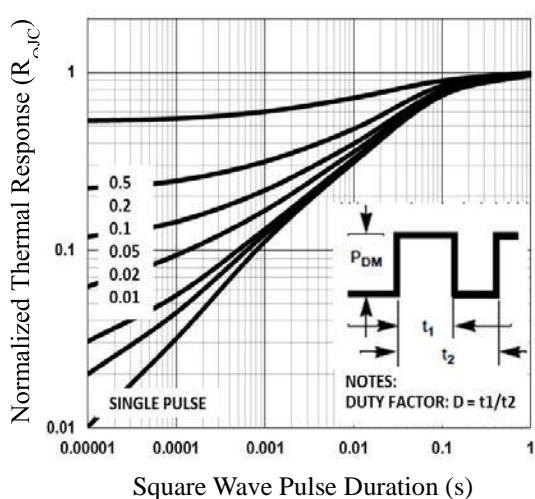
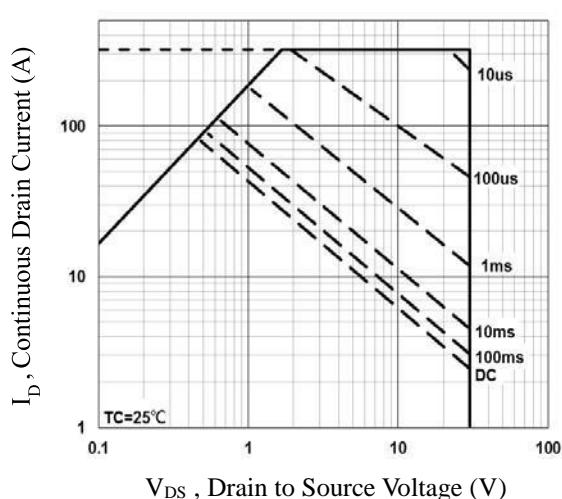
Uninterruptible power supply

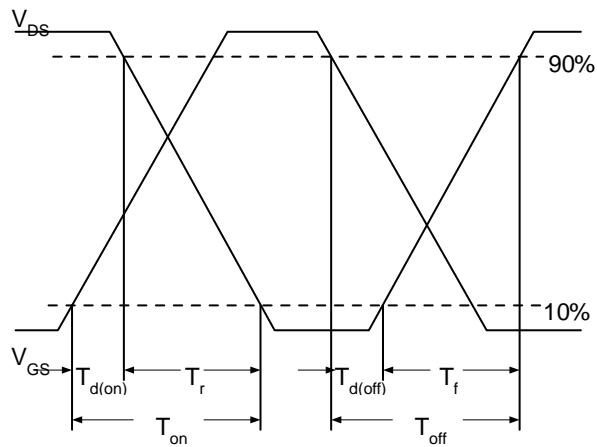
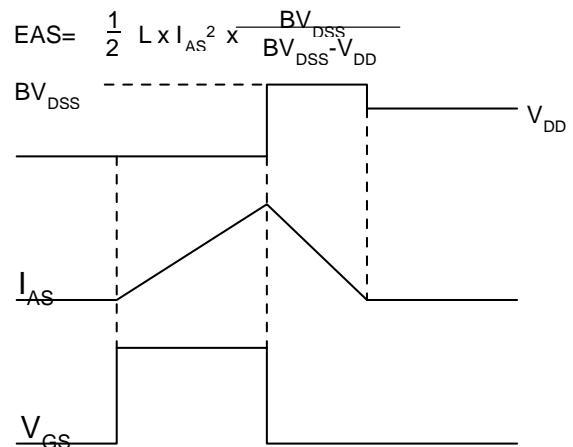
**Absolute Maximum Ratings ( $T_c=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	80	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	51	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	320	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>2</sup>	88	mJ
$I_{AS}$	Single Pulse Avalanche Current <sup>2</sup>	42	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	54	W
	Power Dissipation – Derate above $25^\circ C$	0.43	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction to ambient	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	2.3	$^\circ C/W$

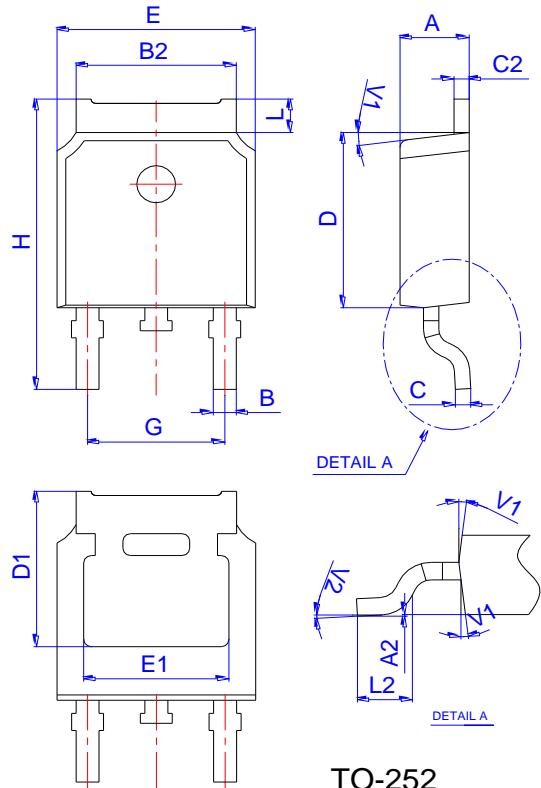
**30V N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$\Delta BVDSS/\Delta TJ$	$BV_{DS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.04	---	$\text{V}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=30\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=24\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
RDS(ON)	Static Drain-Source On-Resistance <sup>3</sup>	$V_{GS}=10\text{V}$ , $I_D=20\text{A}$	---	4.8	6	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=10\text{A}$	---	6.5	9	$\text{m}\Omega$
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D = 250\mu\text{A}$	1	1.6	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-4	---	$\text{mV}/^\circ\text{C}$
gfs	Forward Transconductance	$V_{DS}=10\text{V}$ , $I_D=10\text{A}$	---	18	---	S
Q <sub>g</sub>	Total Gate Charge <sup>3, 4</sup>	$V_{DS}=15\text{V}$ , $V_{GS}=4.5\text{V}$ , $I_D=20\text{A}$	---	11.1	---	nC
Qgs	Gate-Source Charge <sup>3, 4</sup>		---	1.85	---	
Qgd	Gate-Drain Charge <sup>3, 4</sup>		---	6.8	---	
Td(on)	Turn-On Delay Time <sup>3, 4</sup>	$V_{DD}=15\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3.3\Omega$ $I_D=15\text{A}$	---	7.5	---	ns
T <sub>r</sub>	Rise Time <sup>3, 4</sup>		---	14.5	---	
Td(off)	Turn-Off Delay Time <sup>3, 4</sup>		---	35.2	---	
T <sub>f</sub>	Fall Time <sup>3, 4</sup>		---	9.6	---	
Ciss	Input Capacitance	$V_{DS}=25\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	1160	---	pF
Coss	Output Capacitance	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $F=1\text{MHz}$	---	200	---	$\Omega$
Crss	Reverse Transfer Capacitance		---	180	---	
R <sub>g</sub>	Gate resistance		---	2.5	---	
EAS	Single Pulse Avalanche Energy	$V_{DD}=25\text{V}$ , $L=0.1\text{mH}$ , $IAS=20\text{A}$	20	---	---	mJ
IS	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	80	A
ISM	Pulsed Source Current <sup>3</sup>		---	---	320	A
VSD	Diode Forward Voltage <sup>3</sup>	$V_{GS}=0\text{V}$ , $I_S=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
trr	Reverse Recovery Time	$V_{GS}=0\text{V}$ , $I_S=1\text{A}$ , $di/dt=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$	---	---	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge		---	---	---	nC

**30V N-Channel Enhancement Mode MOSFET**

**Fig.1 Continuous Drain Current vs.  $T_c$** 

**Fig.2 Normalized RDS(on) vs.  $T_j$** 

**Fig.3 Normalized  $V_{th}$  vs.  $T_j$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**

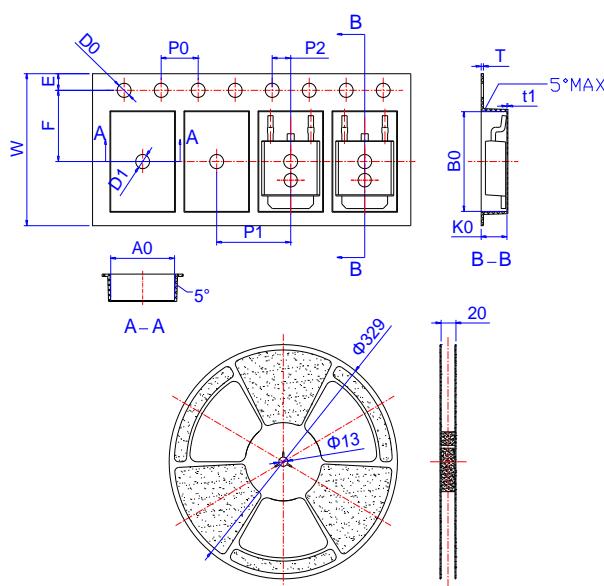
**30V N-Channel Enhancement Mode MOSFET**

**Fig. 7** Switching Time Waveform

**Fig. 8** EAS Waveform

### Package Mechanical Data



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

### Reel Specification-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583